

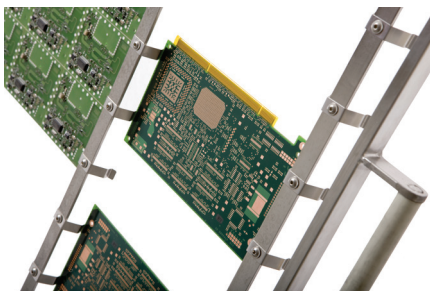
Decotron® CP381 is a **new generation** of water-based cleaning fluid determined to remove flux residues after the soldering from the PCBs. This fluid is designed to **CLEAN and PROTECT** PCBs after soldering.

Decotron® CP381 has **high compatibility with aluminum, copper, dural, other alloys and termotransfer print.**

Decotron® CP381 is used in all the types of cleaning technologies without limitation, thanks to its nonflammability and high material compatibility, mainly in the spray-in-air technologies, ultrasonic and air-based as well.

Areas for Use of Decotron® CP381:

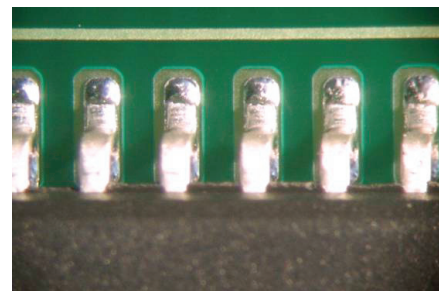
1. unsoldered solder paste – PCB misprints and stencils	recommended	InJet®
2. SMD adhesives, uncured	recommended	InJet®
3. PCBs - lead-free flux residues	highly recommended	InJet®, Sonix®
4. PCBs - no-clean flux residues	highly recommended	InJet®, Sonix®
5. PCBs - resin fluxing agent residues	highly recommended	InJet®, Sonix®
6. hardened conformal coatings	<i>unrecommended</i>	



Misprint



Stencil



Flux residues on PCBs

Cleaning Process Using Decotron® CP381:

- > Decotron® CP381 is intended for direct use, no need to dilute!
- > stir well before use – Decotron® CP381 consists of several components and it is vital that their ratio remains the same in the remaining liquid if it is not used entirely;
- > filtration of the fluid: recommended – to extend the service life of Decotron® CP381 and to protect certain parts of the cleaning device it is suitable to install filtrations of the cleaning bath. For consultation and the proposal please contact your DCT representative.
- > *rinse using normal water – as the water composition and hardness vary substantially in the different places, it is recommended to rinse with normal water only for the cleaning of the soldering frames and machine parts. To rinse PCBs it is highly recommended to use Di-water which would guarantee that no salts and minerals contained in normal water stay on the rinsed surface as these may be dangerous to PCBs in the long run.
- > Pb-free compatible – Decotron® CP381 is developed also for the cleaning of Pb-free solder pastes.

1.1. Flux residues after the soldering - PCBs:

Process stages:	1. <i>cleaning</i>	2. <i>rinse</i>	3. <i>drying</i>
Cleaning fluid:	<i>Decotron® CP381</i>	<i>Di-water (not water)*</i>	<i>air, hot circulating air</i>
Time (in minutes):	<i>5 to 15</i>	<i>2 to 4</i>	<i>10 to 20</i>
Temperature (°C):	<i>from 20, best at 45</i>	<i>room temperature</i>	<i>room temp. to 70</i>

1.2. Flux residues after the soldering + unsoldered solder paste - PCBs' misprints and stencils:

Process stages:	1. <i>cleaning</i>	2. <i>rinse</i>	3. <i>drying</i>
Cleaning fluid:	<i>Decotron® CP381</i>	<i>Di-water (not water)*</i>	<i>air, hot circulating air</i>
Time (in minutes):	<i>5 to 15</i>	<i>2 to 4</i>	<i>10 to 20</i>
Temperature (°C):	<i>from 20, best at 45</i>	<i>room temperature</i>	<i>room temp. to 70</i>

Decotron® CP381 Qualities:

- > highly compatible no negative influence on PCBs materials, stencils and components of the cleaning devices;
- > suitable for closed cleaning processes;
- > no flash point – even if heated extremely no self-ignition occurs, also Decotron® CP381 cannot be set on fire by direct fire;